

# 高精度3次元リフロー加熱特性同定方法の開発

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## Development of Examination of How to Identify Thermal Characteristic for Reflow Soldering

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### Abstract

Lead-free solders are promising alternatives to conventional solders for environmental reasons. However, the range of temperatures which allow the solders to melt without damaging components is narrow. In order to improve quality and reduce the development period, we have developed a reflow analysis system utilizing experiment and simulation.

**Key Words:** Heat Simulation, Reflow Soldering, Lead-Free Solders